Materials Declaration

Package	TSSOP_EP
Body Size	4.4 mm
LeadCount	28
Option	Sn/Pb

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2 Filler	82.00	4.74 E-02	421280
Biphenyl Resin	15.90	9.20 E-03	81687
Sb2O3	1.50	8.68 E-04	7710
Br	0.60	3.47 E-04	3082

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	96.20	4.40 E-02	391007
Ni	3.00	1.37 E-03	12196
Si	0.65	2.97 E-04	2638
Mg	0.15	6.90 E-05	613

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100.0	7.20 E-04	6396

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85.0	2.51 E-03	22261
Pb	15.0	4.42 E-04	3926

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	4.90 E-04	4353

Chip

	% of Chip	Weight (g)	PPM
Si	100.0	3.88 E-03	34474

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag	70.0	6.61 E-04	5872
Diglycidylether of bisphenol-F	10.0	9.40 E-05	835
Resin	7.0	6.60 E-05	586
Amine	5.0	4.70 E-05	417
Gamma Butyrolactone	5.0	4.70 E-05	417
Mixed aryl allyl glycidyl compounds	3.0	2.80 E-05	249

Molding Compound

Item	PPM	Method
Pb	None Detected	EPA3050B. ICP-AES
Cd	None Detected	EPA3050B. ICP-AES
Hg	None Detected	EPA3052B. Mercury Analyzer.
Cr+6	None Detected	EPA3060A & 7196A. UV-VIS
PBB	None Detected	EPA1614. Analysis was performed by GC/MS.
PBDE	None Detected	EPA1614. Analysis was performed by GC/MS.

Die Attach Paste

Item	PPM	Method
Pb	None Detected	US EPA 3050B. Analysis was performed by ICP-AES
Cd	None Detected	EN 1122 Method B. Analysis was performed by ICP-AES
Hg	None Detected	US EPA 3052. Analysis was performed by ICP-AES
Cr+6	None Detected	EPA 3060A & 7196A
PBB	None Detected	US EPA 3540 or 3550. Analysis by HPLC/DAD, LC/MS or
PBDE	None Detected	US EPA 3540 or 3550. Analysis by HPLC/DAD, LC/MS or

Package Totals

Weight (g)	PPM
1.13 E-01	1000000

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ADI Proprietary

Materials Declaration

Package	TSSOP_EP
Body Size	4.4 mm
LeadCount	28
Option	Pb-free

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2 Filler	84.00	4.88 E-02	433060
Multiaromatic Resin	15.90	9.30 E-03	82490

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	96.20	4.40 E-02	390352
Ni	3.00	1.37 E-03	12176
Si	0.65	2.97 E-04	2634
Mg	0.15	6.90 E-05	612

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100.0	7.20 E-04	6385

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100.0	2.72 E-03	24156

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	4.90 E-04	4345

Chip

	% of Chip	Weight (g)	PPM
Si	100.0	3.88 E-03	34417

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag	70.0	7.39 E-04	6553
Resin	21.0	2.22 E-04	1969
Metal Oxide	3.0	3.20 E-05	284
Amine	3.0	3.20 E-05	284
Gamma Butyrolactone	3.0	3.20 E-05	284

Molding Compound

Item	PPM	Method
Pb	None Detected	EPA3050B. ICP-AES
Cd	None Detected	EPA3050B. ICP-AES
Hg	None Detected	EPA3052B. Mercury Analyzer.
Cr+6	None Detected	EPA3060A & 7196A. UV-VIS
PBB	None Detected	EPA1614. Analysis was performed by GC/MS.
PBDE	None Detected	EPA1614. Analysis was performed by GC/MS.

Die Attach Paste

Item	PPM	Method
Pb	None Detected	US EPA 3052. ICP-OES
Cd	None Detected	US EPA 3052. ICP-OES
Hg	None Detected	US EPA 3052. ICP-OES
Cr+6	None Detected	EPA 3060A & 7196A. UV-VIS
PBB	None Detected	Analysis performed by GC/MS
PBDE	None Detected	Analysis performed by GC/MS

Package Totals

Weight (g)	PPM
1.13 E-01	1000000

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